

## Amendments to the Claims

### Claims 1-9 (Canceled)

Claim 10 (Currently Amended) An analog resistive-film type thin-frame touch panel, comprising:

a lower-side electrode member having  
\_\_\_\_\_ a lower-side transparent insulating base member,  
\_\_\_\_\_ a lower-side transparent electrode on a part of a top face of ~~a~~ the lower-side transparent insulating base member,  
\_\_\_\_\_ a pair of lower-side bus bars disposed on two parallel sides of the lower-side transparent electrode, and  
\_\_\_\_\_ lower-side external terminal connection portions disposed on a portion other than the lower-side transparent electrode and connected to the lower-side bus bars; ~~and~~  
an upper-side electrode member having  
\_\_\_\_\_ a flexible upper-side transparent insulating base member,  
\_\_\_\_\_ an upper-side transparent electrode on a part of a bottom face of ~~an~~ the flexible upper-side transparent insulating base member ~~having flexibility,~~  
\_\_\_\_\_ a pair of upper-side bus bars disposed on two parallel sides of the upper-side transparent electrode, and  
\_\_\_\_\_ upper-side external terminal connection portions disposed on a portion other than the upper-side transparent electrode and connected to the upper-side bus ~~bars,~~ bars; and  
\_\_\_\_\_ an insulative spacer, wherein  
the lower-side electrode member and the upper-side electrode member ~~being~~ are disposed facing each other via ~~an~~ the insulative spacer ~~in such a way~~ that the upper-side bus bars and the lower-side bus bars are arranged in a square pattern, and ~~being the lower-side electrode member and the upper-side electrode member are~~ bonded at peripheral portions, wherein  
the lower-side bus bars are formed by metal thin wires having a circular cross section and a wire diameter of 30 to 100  $\mu\text{m}$ , ~~while~~  
\_\_\_\_\_ the upper-side bus bars are formed by metal thin wires having a circular cross section and a wire diameter of 30 to 100  $\mu\text{m}$ , and

~~\_\_\_\_\_ in each of the upper-side electrode member and the lower-side electrode member, the metal thin wires and a portion of each of the upper-side and lower-side transparent insulating base members around the metal thin wires are covered with a conductive paste so that the metal thin wires are respectively fixed onto the upper-side transparent insulating base member and the lower-side transparent insulating base member through a conductive past.~~

**Claim 11 (Previously Presented)** The thin-frame touch panel as defined in Claim 10, wherein the lower-side electrode member further has lower-side routing circuits disposed on the portion other than the lower-side transparent electrode, for connecting the lower-side bus bars and the lower-side external terminal connection portions,

the upper-side electrode member further has upper-side routing circuits disposed on the portion other than the upper-side transparent electrode, for connecting the upper-side bus bars and the upper-side external terminal connection portions, and

the lower-side routing circuits are formed from metal thin wires having a circular cross section and a wire diameter of 30 to 100  $\mu\text{m}$  and the upper-side routing circuits are formed from metal thin wires having a circular cross section and a wire diameter of 30 to 100  $\mu\text{m}$ .

**Claim 12 (Currently Amended)** The thin-frame touch panel as defined in Claim 11, wherein the metal thin wires constituting each of the lower-side routing circuits and the upper-side routing circuits are extended to ~~outsides~~ outside of the lower-side electrode member and the upper-side electrode member to constitute the lower-side external terminal connection portions and the upper-side external terminal connection portions.

**Claim 13 (Currently Amended)** The thin-frame touch panel as defined in Claim 10, wherein ~~\_\_\_\_\_ the lower-side bus bars and the lower-side external terminal connection portions are directly-connected~~ connected, and ~~the lower-side bus bars and the lower-side external terminal connection portions are also formed by~~ from metal thin wires having a circular cross section and a wire diameter of 30 to 100  $\mu\text{m}$ , ~~while~~

~~\_\_\_\_\_ the upper-side bus bars and the upper-side external terminal connection portions are directly-connected~~ connected, and ~~the upper-side bus bars and the upper-side external terminal~~

connection portions are also formed by ~~from~~ metal thin wires having a circular cross section and a wire diameter of 30 to 100  $\mu\text{m}$ , and

the metal thin wires of the upper-side external terminal connection portions and the metal thin wires of the lower-side external terminal connection portions are extended to ~~outsides~~ outside of a region where the lower-side electrode member and the upper-side electrode member are bonded to each other.

**Claim 14 (Canceled)**

**Claim 15 (Currently Amended)** The thin-frame touch panel as defined in Claim ~~10~~, 11, wherein ~~in the upper-side electrode member, the metal thin wires are covered with a conductive paste and fixed onto the upper side transparent insulating base member and in the lower-side electrode member, the metal thin wires are covered with a conductive paste and fixed onto the lower-side transparent insulating base member~~ a part of each of the metal thin wires is respectively embedded in one of the upper-side and lower-side transparent insulating base members by melting and solidification of the upper-side and lower-side transparent insulating base members.

**Claim 16 (Currently Amended)** The thin-frame touch panel as defined in Claim 15, wherein ~~a lower-side covering layer formed by being covered with the conductive paste in at least either one of a of bend portion portions of the lower-side routing circuit circuits and the lower-side bus bar in bars of the lower-side electrode member are covered with the conductive paste to form a lower-side covering layer that has a width 2 to 5 times larger than a the wire diameter of the metal thin wire in wires of the lower-side electrode member, and~~ a lower-side covering layer formed by being covered with the conductive paste in other portions of the lower-side electrode member are covered with the conductive paste to form a lower-side covering layer that has a width 1 to 5 times larger than the wire diameter of the metal thin wire in wires of the lower-side electrode member, while ~~an upper-side covering layer formed by being covered with the conductive paste in at least either one of a of bend portion portions of the upper-side routing circuits and the upper-side bus bars in of the upper-side electrode member are covered with the conductive paste to form an~~

upper-side covering layer that has a width 3 to 5 times larger than a the wire diameter of the metal thin-wire in wires of the upper-side electrode member, and

~~\_\_\_\_\_ an upper-side covering layer formed by being covered with the conductive paste in other portions of the upper-side electrode member are covered with the conductive paste to form an~~  
upper-side covering layer that has a width 2 to 5 times larger than the wire diameter of the metal thin-wire in wires of the upper-side electrode member.

Claim 17 (**Currently Amended**) The thin-frame touch panel as defined in Claim 10, wherein the metal thin wires have a specific resistance value of the metal thin wire is  $20 \times 10^{-6} \Omega \cdot \text{cm}$  or less.

Claim 18 (**Currently Amended**) The thin-frame touch panel as defined in Claim 17, wherein the ~~metal thin wire on the transparent insulating base member and its periphery are covered with a~~  
conductive paste has with a specific resistance value of  $1 \times 10^{-4} \Omega \cdot \text{cm}$  or less.

Claim 19 (**Currently Amended**) The thin-frame touch panel as defined in Claim ~~10~~, 11, wherein ~~a thin frame of the touch panel is an interconnection region in the upper-side transparent insulating base member and the lower-side transparent insulating base member of the touch panel, in which the~~ lower-side and upper-side bus bars, the lower-side and upper-side routing circuits, and the lower-side and upper-side external terminal connection portions are formed at peripheries of the lower-side and upper-side transparent insulating base members and form an interconnection region of the upper-side and lower-side transparent insulating base members, the innerconnection region being formed such that its thin-frame width size as seen from an external form thereof is 2 mm or lower at least on three sides.